

PMP10851 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C6, C11	3	0.047uF	Std	TDK	CAP, CERM, 0.047 µF, 16 V, +/- 10%, X7R, 0402	0402
C2, C3	2	10uF	Std	TDK	CAP, CERM, 10uF, 25V, +/-10%, X5R, 1206	1206
C4, C9, C15	3	22uF	Std	TDK	CAP, CERM, 22uF, 16V, +/-20%, X5R, 1206	1206
C5, C7, C8	3	2200pF	Std	TDK	CAP, CERM, 2200 pF, 50 V, +/- 10%, X7R, 0402	0402
C10	1	1uF	Std	TDK	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603
C12, C13, C14	3	0.01uF	Std	TDK	CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0402	0402
J1, J2, J3, J4	4		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
L1, L2, L3	3	2.2uH	VLCF5020T-2R2N2R6-3	TDK	Inductor, Shielded, Ferrite, 2.2 µH, 2.62 A, 0.043 ohm, SMD	5x2x5mm
R1	1	45.3k	Std	Rhom	RES, 45.3 k, 1%, 0.063 W, 0402	0402
R2, R6, R19	3	20.0k	Std	Rhom	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R3, R4, R5, R7,	6	10.0k	Std	Rhom	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R8, R9						
R10, R11, R15	3	49.9	Std	Rhom	RES, 49.9, 1%, 0.063 W, 0402	0402
TP1, TP2, TP3,	4	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
TP4				-		Testpoint
TP5, TP6, TP7,	4	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
TP8				-		Testpoint
U1	1		TPS65263-Q1	Texas Instruments	4.5V to 18V Input Voltage, 3A/2A/2A Output Current Triple Synchronous	RHB0032E
					Step-Down Converter with I2C Controlled Dynamic Voltage Scaling,	
					RHB0032E	

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